

## COPY OF PAPERS **ORIGINALLY FILED**

Examiner:

A. Chambliss

TECHNOLOGY CENTER 2800

Art Unit: 2814

## STATES PATENT AND TRADEMARK OFFICE

Applicants

K. TATSUMI et al.

Serial No.

09/254,118

Filed

May 19, 1999

For

METHOD OF PARTIALLY PLATING SUBSTRATE FOR

ELECTRONIC DEVICES

Assistant Commissioner

for Patents

Washington, D.C. 20231

## TRANSMITTAL LETTER

SIR:

Transmitted herewith is an Amendment/Response in the above-identified patent application.

No additional fee is required. [X]

The fee has been calculated as shown below.

OTHER THAN A SMALL ENTITY SMALL ENTITY CLAIMS HIGHEST NO. RATE ADDIT. OR RATE ADDIT. REMAINING PREVIOUSLY PRESENT FEE FEE AFTER PAID FOR **EXTRA** AMENDMENT TOTAL MINUS 20 x6 = x18 =0 INDEP. MINUS 0.00 3 x18 == 08x[ ]FIRST PRESENTATION OF MULTIPLE x60 = 0.00 x270 =DEP. CLAIM TOTAL ADDIT. FEE 0.00

[X]The Commissioner is hereby authorized to charge fees 37 CFR 1.16 and 1.17 which may be required to Deposit Account 11-0600. A duplicate of this paper is enclosed.

[X]A petition for a two (2) month extension of time and Deposit Account authorization to cover the extension fee are enclosed.

Respectfully submitted,

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on March 22, 2002

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